CLAIMS

1. A connector coupled to provide at least one signal to a board module, comprising:

a connector lead surface substantially perpendicular to a board module surface;

a first row of leads substantially parallel to and a first distance from the board module surface extending substantially perpendicular from the connector lead surface and shaped to connect substantially perpendicular to the board module surface at a second distance from the connector lead surface; and

a second row of leads substantially parallel to and a third distance from the board module surface extending substantially perpendicular from the connector lead surface and shaped to connect substantially perpendicular to the board module surface at a fourth distance from the connector lead surface, wherein the first distance is greater than the third distance, wherein the second distance is less than the fourth distance, and wherein each of the second row of leads are offset from each of the first row of leads.

2. The connector of claim 1, wherein the connector is coupled to communicatively couple the board module a backplane.

3. The connector of claim 1, wherein the connector is coupled to provide at least one power signal to a switch module.

4. The connector of claim 1, wherein the connector is coupled to provide at least one power signal to a VMEbus switch module.

5. The connector of claim 1, wherein the connector is coupled to provide at least one power signal to a VXS switch module.

6. The connector of claim 1, wherein each of the second row of leads are offset from each of the first row of leads in a direction parallel to the board module surface.

7. A board module, comprising:

a board module surface;

a connector coupled to the board module surface, wherein the connector is coupled to provide at least one signal to the board module wherein the connector comprises:

a connector lead surface substantially perpendicular to the board module surface;

a first row of leads substantially parallel to and a first distance from the board module surface extending substantially perpendicular from the connector lead surface and shaped to connect substantially perpendicular to the board module surface at a second distance from the connector lead surface; and

a second row of leads substantially parallel to and a third distance from the board module surface extending substantially perpendicular from the connector lead surface and shaped to connect substantially perpendicular to the board module surface at a fourth distance from the connector lead surface, wherein the first distance is greater than the third distance, wherein the second distance is less than the fourth distance, and wherein each of the second row of leads are offset from each of the first row of leads.

8. The board module of claim 7, wherein the connector is coupled to communicatively couple the board module a backplane.

9. The board module of claim 7, wherein the board module is a switch module, and wherein the connector is coupled to provide at least one power signal to the switch module.

10. The board module of claim 7, wherein the board module is a VME switch module, and wherein the connector is coupled to provide at least one power signal to the VMEbus switch module.

11. The board module of claim 7, wherein the board module is a VXS switch module, and wherein the connector is coupled to provide at least one power signal to a VXS switch module.

12. The board module of claim 7, wherein each of the second row of leads are offset from each of the first row of leads in a direction parallel to the board module surface.

13. A switch module, comprising:

a switch module surface;

a connector coupled to the switch module surface, wherein the connector is coupled to provide at least one signal to the switch module wherein the connector comprises:

a connector lead surface substantially perpendicular to the switch module surface;

a first row of leads substantially parallel to and a first distance from the switch module surface extending substantially perpendicular from the connector lead surface and shaped to connect substantially perpendicular to the switch module surface at a second distance from the connector lead surface; and

a second row of leads substantially parallel to and a third distance from the switch module surface extending substantially perpendicular from the connector lead surface and shaped to connect substantially perpendicular to the switch module surface at a fourth distance from the connector lead surface, wherein the first distance is greater than the third distance, wherein the second distance is less than the fourth distance, and wherein each of the second row of leads are offset from each of the first row of leads.

14. The switch module of claim 13, wherein the connector is coupled to communicatively couple the switch module a backplane.

15. The switch module of claim 13, wherein the connector is coupled to provide at least one power signal to the switch module.

16. The switch module of claim 13, wherein the switch module is a VME switch module, and wherein the connector is coupled to provide at least one power signal to the VMEbus switch module.

17. The switch module of claim 13, wherein the switch module is a VXS switch module, and wherein the connector is coupled to provide at least one power signal to a VXS switch module.

18. The switch module of claim 13, wherein each of the second row of leads are offset from each of the first row of leads in a direction parallel to the switch module surface.

19. A payload module, comprising:

a payload module surface;

a connector coupled to the payload module surface, wherein the connector is coupled to provide at least one signal to the payload module wherein the connector comprises:

a connector lead surface substantially perpendicular to the payload module surface;

a first row of leads substantially parallel to and a first distance from the payload module surface extending substantially perpendicular from the connector lead surface and shaped to connect substantially perpendicular to the payload module surface at a second distance from the connector lead surface; and

a second row of leads substantially parallel to and a third distance from the payload module surface extending substantially perpendicular from the connector lead surface and shaped to connect substantially perpendicular to the payload module surface at a fourth distance from the connector lead surface, wherein the first distance is greater than the third distance, wherein the second distance is less than the fourth distance, and wherein each of the second row of leads are offset from each of the first row of leads.

20. The payload module of claim 19, wherein each of the second row of leads are offset from each of the first row of leads in a direction parallel to the payload module surface.